

Advanced Power MOSFET

SSS6N70A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ $V_{DS} = 700V$
- Low $R_{DS(ON)}$: 1.552 Ω (Typ.)

$BV_{DSS} = 700 V$

$R_{DS(on)} = 1.8 \Omega$

$I_D = 4 A$

TO-220F



1.Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	700	V
I_D	Continuous Drain Current ($T_c=25^\circ C$)	4	A
	Continuous Drain Current ($T_c=100^\circ C$)	2.5	
I_{DM}	Drain Current-Pulsed	24	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	560	mJ
I_{AR}	Avalanche Current	4	A
E_{AR}	Repetitive Avalanche Energy	4	mJ
dv/dt	Peak Diode Recovery dv/dt	2.5	V/ns
P_D	Total Power Dissipation ($T_c=25^\circ C$)	40	W
	Linear Derating Factor	0.32	W/C
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	3.13	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	



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Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	700	--	--	V	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.79	--	V/°C	$I_D=250\mu\text{A}$ See Fig 7
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{\text{DS}}=5\text{V}, I_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$V_{\text{GS}}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$V_{\text{GS}}=-30\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	25	μA	$V_{\text{DS}}=700\text{V}$
		--	--	250		$V_{\text{DS}}=560\text{V}, T_C=125^\circ\text{C}$
$R_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	1.8	Ω	$V_{\text{GS}}=10\text{V}, I_D=2\text{A}$ ④*
g_{fs}	Forward Transconductance	--	3.22	--	S	$V_{\text{DS}}=50\text{V}, I_D=2\text{A}$ ④
C_{iss}	Input Capacitance	--	920	1200	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	100	115		
C_{rss}	Reverse Transfer Capacitance	--	45	55		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	18	45	ns	$V_{\text{DD}}=350\text{V}, I_D=6\text{A},$ $R_G=11.5\text{ }\bullet$ See Fig 13 ④ ⑤
t_r	Rise Time	--	23	55		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	76	160		
t_f	Fall Time	--	26	60		
Q_g	Total Gate Charge	--	51	67	nC	$V_{\text{DS}}=560\text{V}, V_{\text{GS}}=10\text{V},$ $I_D=6\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	8.3	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	23.1	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	4	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	24		
V_{SD}	Diode Forward Voltage ④	--	--	1.4	V	$T_J=25^\circ\text{C}, I_S=4\text{A}, V_{\text{GS}}=0\text{V}$
t_r	Reverse Recovery Time	--	440	--	ns	$T_J=25^\circ\text{C}, I_F=6\text{A}$ ④
Q_{rr}	Reverse Recovery Charge	--	4.05	--	μC	$dI_F/dt=100\text{A}/\mu\text{s}$

Notes :

- Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- $L=65\text{mH}, I_{AS}=4\text{A}, V_{DD}=50\text{V}, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- $I_{SD}\leq 6\text{A}, di/dt\leq 140\text{A}/\mu\text{s}, V_{DD}\leq \text{BV}_{\text{DSS}}$, Starting $T_J=25^\circ\text{C}$
- Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

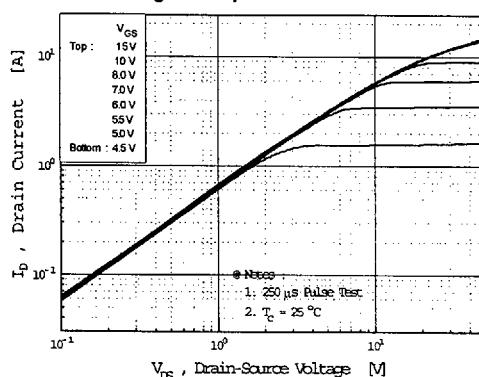


Fig 2. Transfer Characteristics

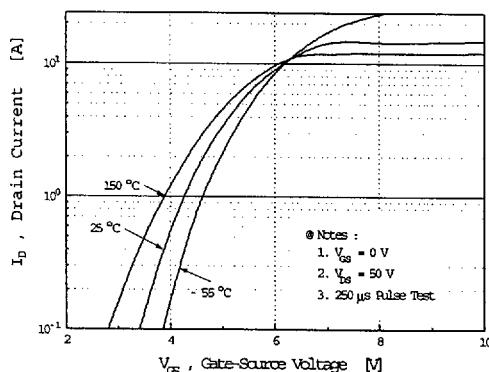


Fig 3. On-Resistance vs. Drain Current

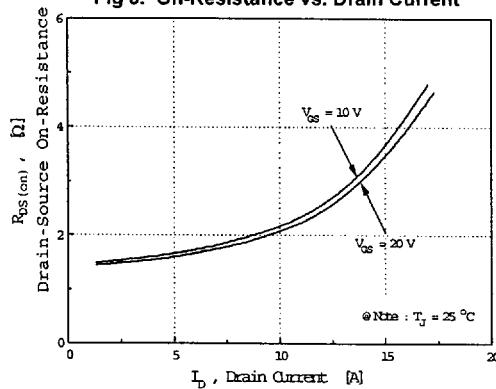


Fig 4. Source-Drain Diode Forward Voltage

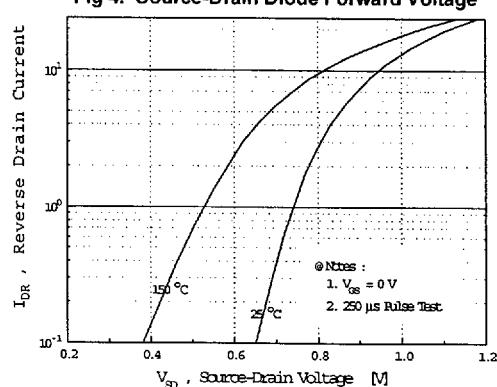


Fig 5. Capacitance vs. Drain-Source Voltage

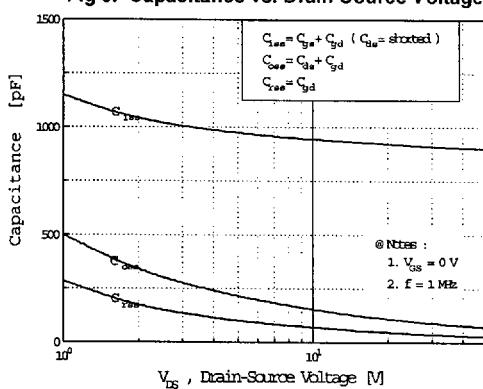
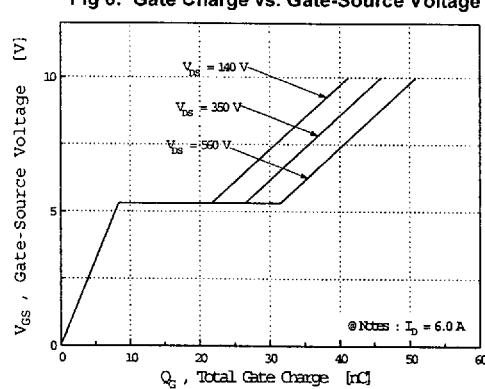


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 7. Breakdown Voltage vs. Temperature

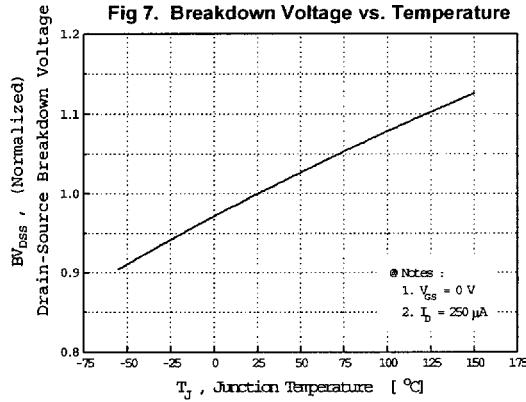


Fig 8. On-Resistance vs. Temperature

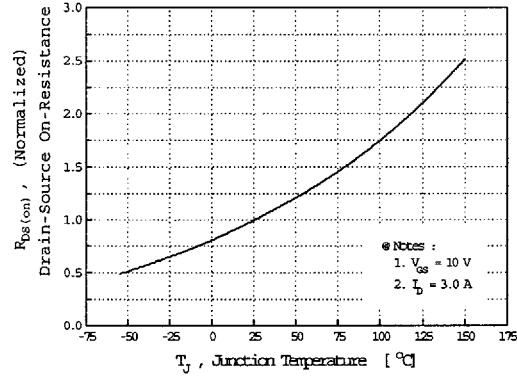


Fig 9. Max. Safe Operating Area

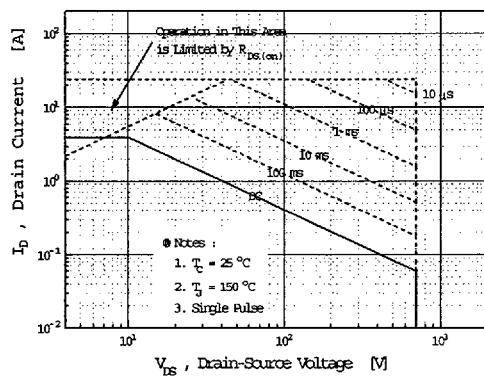


Fig 10. Max. Drain Current vs. Case Temperature

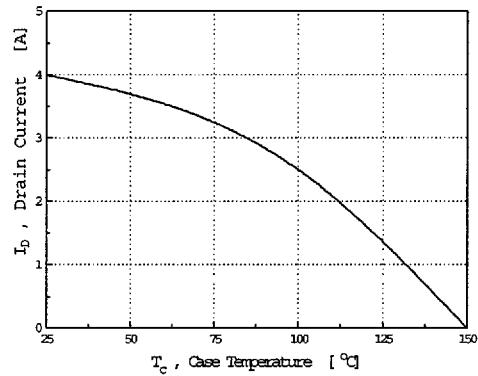
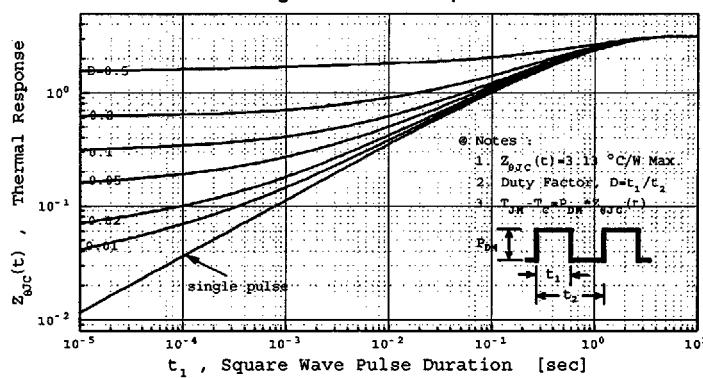


Fig 11. Thermal Response



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Fig 12. Gate Charge Test Circuit & Waveform

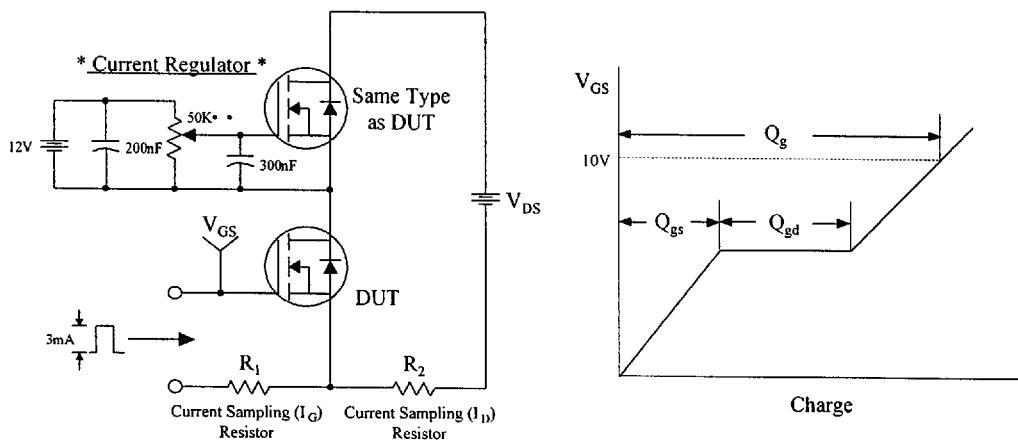


Fig 13. Resistive Switching Test Circuit & Waveforms

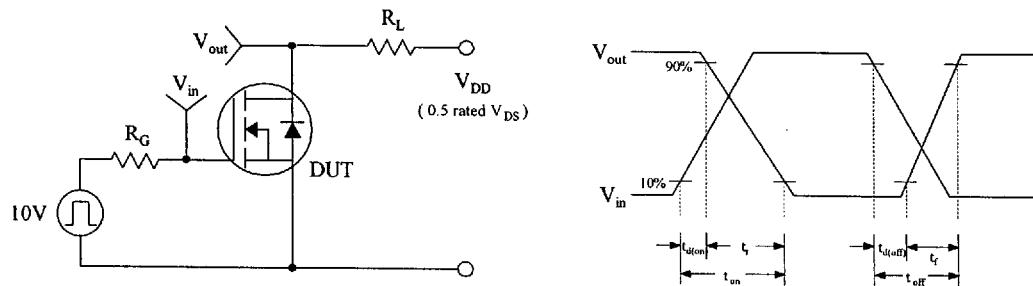


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

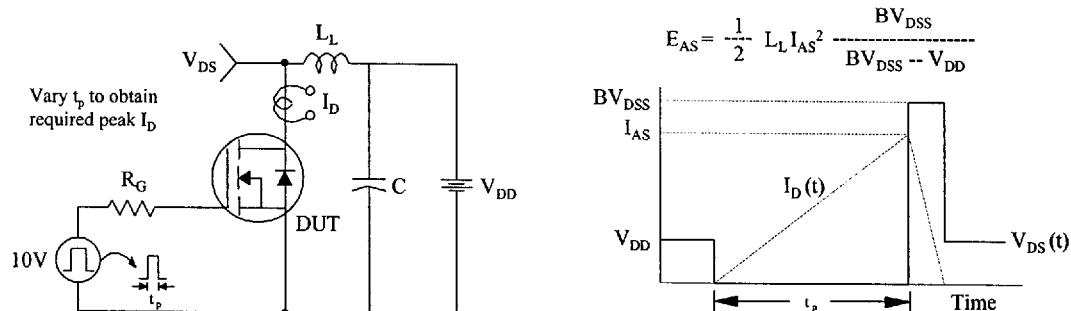


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

